

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A multi-layer printed wiring board ~~in which an interlayer insulating layer and a conductive layer are formed on both sides or a single side of~~ comprising:

a core substrate having a plurality of through holes therein, and electric connection is carried out through via holes, the through holes in the core substrate being disposed so that a ground through hole and a power through hole adjoin each other, wherein a distance between the ground through hole and the power through hole is in a range of 60 to 550 μ m;

an interlayer insulating layer formed on the core substrate;

a conductive layer formed on the interlayer insulating layer; and

a plurality of via holes provided in the insulating layer and configured to provide electrical connection between the conductive layer and through holes.

Claim 2 (Currently Amended): ~~[[A]] The multi-layer printed wiring board according to claim 1, wherein in which an interlayer insulating layer and a conductive layer are formed on both sides or a single side of a core substrate having a plurality of through holes and electric connection is carried out through via holes,~~

the ground through holes hole in the core substrate including two or more ground through holes and the power through hole including two or more power through holes, such that the ground through ~~hole~~ holes and the power through ~~hole~~ holes are disposed in a grid formation or in a staggered formation at adjacent positions.

Claim 3 (Canceled).

Claim 4 (Currently Amended): The multi-layer printed wiring board according to ~~any one of claims 1 to 3~~ claim 1, wherein the diameter of the ground through hole is 50 to 500 μm and the diameter of the power through hole is 50 to 500 μm .

Claim 5 (Currently Amended): The multi-layer printed wiring board according to claim 1, ~~[[or 2]]~~ wherein ~~in~~ at least one through hole of the ground through holes and the power through holes comprises ~~one or two or more through holes are~~ in a stack structure through all ~~entire~~ layers of the multi-layer printed wiring board up to ~~the~~ an outermost layer.

Claim 6 (Original): The multi-layer printed wiring board according to any one of claims 1, 2 or 5 wherein the ground through hole and the power through hole are disposed just below an IC chip.

Claim 7 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein the thickness of conductive layer on the core substrate is larger than the thickness of the conductive layer on the interlayer insulating layer.

Claim 8 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein assuming that the thickness of the conductive layer on the core substrate is α_1

1 and the thickness of the conductive layer on the interlayer insulating layer is α_2 , $\alpha_2 < \alpha_1 \leq 40\alpha_2$.

Claim 9 (Original): The multi-layer printed wiring board according to claim 8 wherein the α_1 is in a relation of $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 10 (Currently Amended): The multi-layer printed wiring board according to ~~any one of claims 7 to 9~~ claim 7, wherein each conductive layer of the core substrate is conductive layer for power layer or conductive layer for grounding.

Claim 11 (Currently Amended): The multi-layer printed wiring board according to ~~any one of claims 1, 2, 7 to 10~~ claim 1, wherein a capacitor is mounted on the surface thereof.

Claim 12 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein the core substrate is a multi-layer core substrate composed of three or more layers and including a thick conductive layer as an inner layer, and

the conductive layer of each inner layer of the core substrate and the conductive layer of each surface are conductive layer for power layer or conductive layer for grounding.

Claim 13 (Original): The multi-layer printed wiring board according to claim 1 or 2 wherein the core substrate is a multi-layer core substrate composed of three layers and including a thick conductive layer as an inner layer, and

the conductive layer of each inner layer of the core substrate is conductive layer for power layer or conductive layer for grounding and the conductive layer on the front surface side is composed of signal line.

Claim 14 (Currently Amended): The multi-layer printed wiring board according to claim 12, [[or 13]] wherein the thickness of the conductive layer of the inner layer of the core substrate is larger than the thickness of the conductive layer on the interlayer insulating layer.

Claim 15 (Original): The multi-layer printed wiring board according to claim 12 or 13 wherein the conductive layer in the inner layer of the core substrate is composed of two or more layers.

Claim 16 (Currently Amended): The multi-layer printed wiring board according to claim 12, [[or 13]] wherein the core substrate is so constructed that the conductive layer of the inner layer is formed on each of both sides of a metallic plate electrically insulating, through resin layer and further, the conductive layer on the surface side is formed outside the conductive layer of the inner layer through resin layer.

Claim 17 (Currently Amended): The multi-layer printed wiring board according to ~~any one of claims 12 to 16~~ claim 12, wherein the core substrate is so constructed that a thick conductive layer is disposed as the inner layer and a thin conductive layer is disposed on the surface side.